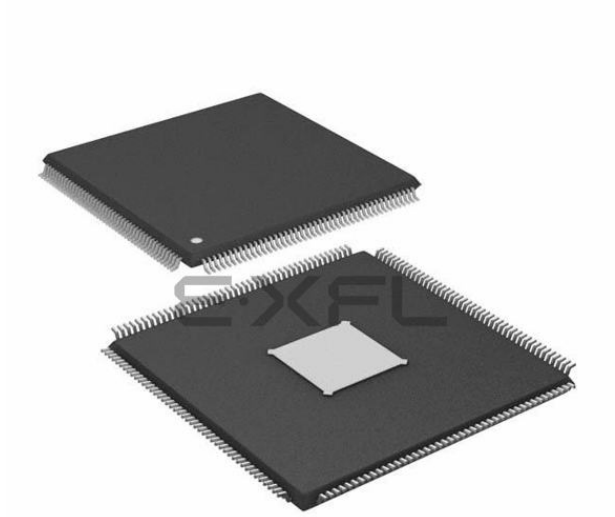

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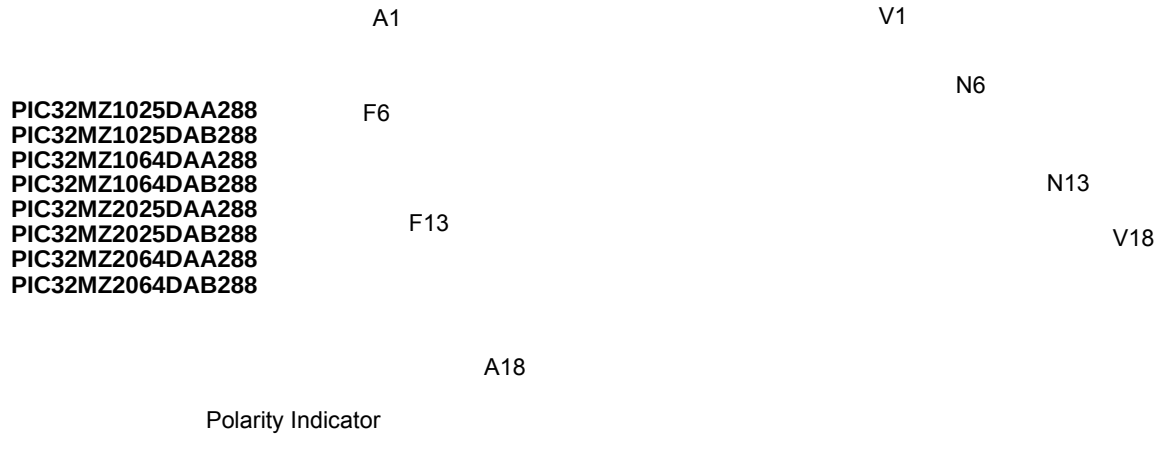
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® microAptiv™
Core Size	32-Bit Single-Core
Speed	200MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, LINbus, PMP, SPI, SQI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, HLVD, I²S, POR, PWM, WDT
Number of I/O	120
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	640K x 8
Voltage - Supply (Vcc/Vdd)	1.7V ~ 3.6V
Data Converters	A/D 45x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	176-LQFP Exposed Pad
Supplier Device Package	176-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mz1064dah176-i-2j

TABLE 7: PIN NAMES FOR 288-PIN DEVICES (CONTINUED)

288-PIN LFBGA (BOTTOM VIEW)



PIC32MZ1025DAA288
PIC32MZ1025DAB288
PIC32MZ1064DAA288
PIC32MZ1064DAB288
PIC32MZ2025DAA288
PIC32MZ2025DAB288
PIC32MZ2064DAA288
PIC32MZ2064DAB288

Ball/Pin Number	Full Pin Name
V3	DDRA15
V4	VDDCORE
V5	RTCC/RPD0/RD0
V6	SCK4/RD10
V7	GD6/EBIA11/RPF0/PMA11/RF0
V8	GD21/EBIA23/RH15
V9	GD3/EBIA8/RPG0/PMA8/RG0
V10	EBID2/PMD2/RE2
V11	ERXDV/ECRSDV/RH13
V12	ERXD3/RH9
V13	ETXD2/RH0
V14	ETXD0/RJ8
V15	ETXERR/RJ0
V16	ETXEN/RPD6/RD6
V17	GD1/EBID14/PMD14/RA4
V18	No Connect

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 and Table 4 for the available peripherals and **12.4 "Peripheral Pin Select (PPS)"** for restrictions.

2: Every I/O port pin (RAx-RKx) can be used as a change notification pin (CNAx-CNKx). See **12.0 "I/O Ports"** for more information.

3: Shaded pins are 5V tolerant.

4: This pin must be tied to Vss through a 20k Ω resistor when DDR is not connected in the system.

5: This pin is a No Connect when DDR is not connected in the system.

6: These pins are restricted to input functions only.

2.6 Trace

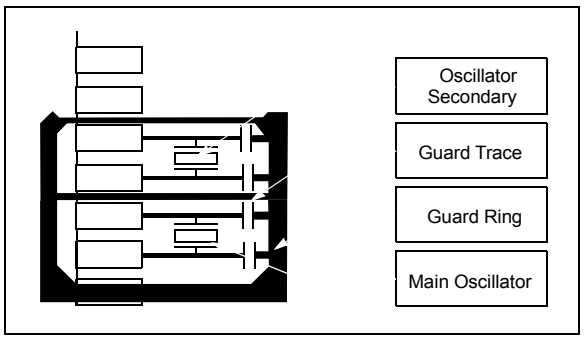
The trace pins can be connected to a hardware trace-enabled programmer to provide a compressed real-time instruction trace. When used for trace, the TRD3, TRD2, TRD1, TRD0 and TRCLK pins should be dedicated for this use. The trace hardware requires a 22 Ohm series resistor between the trace pins and the trace connector.

2.7 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT



2.7.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- CIN = PIC32_OSC2_pin capacitance = 4 pF
- COUT = PIC32_OSC1_pin capacitance = 4 pF
- PCB stray capacitance (i.e., 12 mm length) = 2.5 pF
- C1 and C2 are the loading capacitors to use on your Crystal circuit design to guarantee that the effective capacitance as seen by the crystal in circuit meets the crystal manufacturer specification.

From the Crystal manufacturer CLOAD spec:

CLOAD = {([Cin + C1] * [COUT + C2]) / [Cin + C1 + C2 + COUT] } + oscillator PCB stray capacitance

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer data sheet spec example: C_{LOAD} = 15 *pF*

Therefore:

MFG C_{LOAD} = {([C_{IN} + *C1*] * [C_{OUT} + *C2*]) / [C_{IN} + *C1* + *C2* + C_{OUT}] } + *estimated oscillator PCB stray capacitance*

Assuming *C1 = C2* and PIC32 *Cin = Cout*, the formula can be further simplified and restated to solve for *C1* and *C2* by:

*C1 = C2 = ((2 * MFG Cload spec) - Cin - (2 * PCB capacitance))*
*= ((2 * 15) - 4 - (2 * 2.5 pF))*
= (30 - 4 - 5)
= 21 pF

Therefore:

C1 = C2 = 21 pF is the correct loading capacitors to use on your crystal circuit design to guarantee that the effective capacitance as seen by the crystal in circuit in this example is 15 pF to meet the crystal manufacturer specification.

Note: Do not add excessive gain such that the oscillator signal is clipped flat on top of the sine wave. If your oscillator signal is clipped, reduce the gain or add a series resistor (RS) as shown in the "Circuit A" of the Figure 2-4. Failure to do so will stress and reduce the lifetime of the crystal, which might result in a premature failure. When measuring the oscillator signal, the user must use an active-powered scope probe with ≤ 1 pF or the scope probe itself will unduly change the gain and Peak-to-Peak oscillator signal levels.

2.7.1.1 Additional Microchip References

- AN588 *"PICmicro® Microcontroller Oscillator Design Guide"*
- AN826 *"Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices"*
- AN849 *"Basic PICmicro® Oscillator Design"*

REGISTER 4-6: SBTxELOG1: SYSTEM BUS TARGET 'x' ERROR LOG REGISTER 1 ('x' = 0-13) (CONTINUED)

bit 15-8 **INITID<7:0>:** Initiator ID of Requester bits
11111111 = Reserved
.
.
.
00001111 = Reserved
00001110 = SDHC
00001101 = GPU
00001100 = GLCD
00001011 = Crypto Engine
00001010 = Flash Controller
00001001 = SQI1
00001000 = CAN2
00000111 = CAN1
00000110 = Ethernet Write
00000101 = Ethernet Read
00000100 = USB
00000011 = DMA Write
00000010 = DMA Read
00000001 = CPU
00000000 = Reserved

bit 7-4 **REGION<3:0>:** Requested Region Number bits
1111 - 0000 = Target's region that reported a permission group violation

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **CMD<2:0>:** Transaction Command of the Requester bits
111 = Reserved
110 = Reserved
101 = Write (a non-posted write)
100 = Reserved
011 = Read (a locked read caused by a Read-Modify-Write transaction)
010 = Read
001 = Write
000 = Idle

Note: Refer to Table 4-8 for the list of available targets and their descriptions.

TABLE 7-3: INTERRUPT REGISTER MAP (CONTINUED)

Virtual Address (BF81_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
07FC	OFF175	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0800	OFF176	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0804	OFF177	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0808	OFF178	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
080C	OFF179	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0810	OFF180	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0814	OFF181	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0818	OFF182	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
081C	OFF183	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0820	OFF184	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0824	OFF185	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0828	OFF186	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
082C	OFF187	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0830	OFF188	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0834	OFF189	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0838	OFF190	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
083C	OFF191	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0840	OFF192	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000
0844	OFF193	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	VOFF<17:16>		0000
		15:0	VOFF<15:1>															—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table with the exception of the OFFx registers, have corresponding CLR, SET, and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

2: This bit is only available on devices with a Crypto module.

8.0 OSCILLATOR CONFIGURATION

Note: This data sheet summarizes the features of the PIC32MZ DA family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 42. "Oscillators with Enhanced PLL"** (DS60001250) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

The PIC32MZ DA oscillator system has the following modules and features:

- Five external and internal oscillator options as clock sources
- On-Chip PLL with user-selectable input divider, multiplier and output divider to boost operating frequency on select internal and external oscillator sources
- On-Chip user-selectable divisor postscaler on select oscillator sources
- Software-controllable switching between various clock sources
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown with dedicated Back-up FRC (BFRC)
- Dedicated On-Chip PLL for DDR2 and USB modules
- Flexible reference clock output
- Multiple clock branches for peripherals for better performance flexibility

A block diagram of the oscillator system is provided in Figure 8-1. The clock distribution is shown in Table 8-1.

REGISTER 8-7: SLEWCON: OSCILLATOR SLEW CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	SYSDIV<3:0>(1)			
15:8	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	—	SLWDIV<2:0>		
7:0	U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R-0, HS, HC
	—	—	—	—	—	UPEN	DNEN	BUSY

Legend:	HC = Hardware Cleared	HS = Hardware Set	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-20 **Unimplemented:** Read as '0'

bit 19-16 **SYSDIV<3:0>:** System Clock Divide Control bits(1)

1111 = SYSCLK is divided by 16
1110 = SYSCLK is divided by 15
.
.
.
0010 = SYSCLK is divided by 3
0001 = SYSCLK is divided by 2
0000 = SYSCLK is not divided

bit 15-11 **Unimplemented:** Read as '0'

bit 10-8 **SLWDIV<2:0>:** Slew Divisor Steps Control bits

These bits control the maximum division steps used when slewing during a frequency change.
111 = Steps are divide by 128, 64, 32, 16, 8, 4, 2, and then no divisor
110 = Steps are divide by 64, 32, 16, 8, 4, 2, and then no divisor
101 = Steps are divide by 32, 16, 8, 4, 2, and then no divisor
100 = Steps are divide by 16, 8, 4, 2, and then no divisor
011 = Steps are divide by 8, 4, 2, and then no divisor
010 = Steps are divide by 4, 2, and then no divisor
001 = Steps are divide by 2, and then no divisor
000 = No divisor is used during slewing
The steps apply in reverse order (i.e., 2, 4, 8, etc.) during a downward frequency change.

bit 7-3 **Unimplemented:** Read as '0'

bit 2 **UPEN:** Upward Slew Enable bit

1 = Slewing enabled for switching to a higher frequency
0 = Slewing disabled for switching to a higher frequency

bit 1 **DNEN:** Downward Slew Enable bit

1 = Slewing enabled for switching to a lower frequency
0 = Slewing disabled for switching to a lower frequency

bit 0 **BUSY:** Clock Switching Slewing Active Status bit

1 = Clock frequency is being actively slewed to the new frequency
0 = Clock switch has reached its final value

Note 1: The SYSDIV<3:0> bit settings are ignored if both UPEN and DNEN = 0, and SYSCLK will be divided by 1.

TABLE 11-1: USB REGISTER MAP 1 (CONTINUED)

Virtual Address	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
309C	USB E3RXA	31:16	—	RXHUBPRT<6:0>							MULTTRAN	RXHUBADD<6:0>							0000
		15:0	—	—	—	—	—	—	—	—	—	RXFADDR<6:0>							0000
30A0	US BE4TXA	31:16	—	TXHUBPRT<6:0>							MULTTRAN	TXHUBADD<6:0>							0000
		15:0	—	—	—	—	—	—	—	—	—	TXFADDR<6:0>							0000
30A4	USB E4RXA	31:16	—	RXHUBPRT<6:0>							MULTTRAN	RXHUBADD<6:0>							0000
		15:0	—	—	—	—	—	—	—	—	—	RXFADDR<6:0>							0000
30A8	USB E5TXA	31:16	—	TXHUBPRT<6:0>							MULTTRAN	TXHUBADD<6:0>							0000
		15:0	—	—	—	—	—	—	—	—	—	TXFADDR<6:0>							0000
30AC	USB E5RXA	31:16	—	RXHUBPRT<6:0>							MULTTRAN	RXHUBADD<6:0>							0000
		15:0	—	—	—	—	—	—	—	—	—	RXFADDR<6:0>							0000
30B0	USB E6TXA	31:16	—	TXHUBPRT<6:0>							MULTTRAN	TXHUBADD<6:0>							0000
		15:0	—	—	—	—	—	—	—	—	—	TXFADDR<6:0>							0000
30B4	USB E6RXA	31:16	—	RXHUBPRT<6:0>							MULTTRAN	RXHUBADD<6:0>							0000
		15:0	—	—	—	—	—	—	—	—	—	RXFADDR<6:0>							0000
30B8	USB E7TXA	31:16	—	TXHUBPRT<6:0>							MULTTRAN	TXHUBADD<6:0>							0000
		15:0	—	—	—	—	—	—	—	—	—	TXFADDR<6:0>							0000
30BC	USB E7RXA	31:16	—	RXHUBPRT<6:0>							MULTTRAN	RXHUBADD<6:0>							0000
		15:0	—	—	—	—	—	—	—	—	—	RXFADDR<6:0>							0000
3100	USB E0CSR0	31:16	Indexed by the same bits in USBIE0CSR0																0000
		15:0																	0000
3108	USB E0CSR2	31:16	Indexed by the same bits in USBIE0CSR2																0000
		15:0																	0000
310C	USB E0CSR3	31:16	Indexed by the same bits in USBIE0CSR3																0000
		15:0																	0000
3110	USB E1CSR0	31:16	Indexed by the same bits in USBIE1CSR0																0000
		15:0																	0000
3114	USB E1CSR1	31:16	Indexed by the same bits in USBIE1CSR1																0000
		15:0																	0000
3118	USB E1CSR2	31:16	Indexed by the same bits in USBIE1CSR2																0000
		15:0																	0000
311C	USB E1CSR3	31:16	Indexed by the same bits in USBIE1CSR3																0000
		15:0																	0000
3120	USB E2CSR0	31:16	Indexed by the same bits in USBIE2CSR0																0000
		15:0																	0000
3124	USB E2CSR1	31:16	Indexed by the same bits in USBIE2CSR1																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Device mode.
2: Host mode.
3: Definition for Endpoint 0 (ENDPOINT<3:0> (USBCSR<19:16>) = 0).
4: Definition for Endpoints 1-7 (ENDPOINT<3:0> (USBCSR<19:16>) = 1 through 7).

REGISTER 11-9: USBIENCSR1: USB INDEXED ENDPOINT CONTROL STATUS REGISTER 1 (ENDPOINT 1-7) (CONTINUED)

bit 18 **OVERRUN:** Data Overrun Status bit (*Device mode*)

1 = An OUT packet cannot be loaded into the RX FIFO.

0 = Written by software to clear this bit

This bit is only valid when the endpoint is operating in ISO mode. In Bulk mode, it always returns zero.

ERROR: No Data Packet Received Status bit (*Host mode*)

1 = Three attempts have been made to receive a packet and no data packet has been received. An interrupt is generated.

0 = Written by the software to clear this bit.

This bit is only valid when the RX endpoint is operating in Bulk or Interrupt mode. In ISO mode, it always returns zero.

bit 17 **FIFOFULL:** FIFO Full Status bit

1 = No more packets can be loaded into the RX FIFO

0 = The RX FIFO has at least one free space

bit 16 **RXPKTRDY:** Data Packet Reception Status bit

1 = A data packet has been received. An interrupt is generated.

0 = Written by software to clear this bit when the packet has been unloaded from the RX FIFO.

bit 15-11 **MULT<4:0>:** Multiplier Control bits

For Isochronous/Interrupt endpoints or of packet splitting on Bulk endpoints, multiplies TXMAXP by MULT+1 for the payload size.

For Bulk endpoints, MULT can be up to 32 and defines the number of “USB” packets of the specified payload into which a single data packet placed in the FIFO should be split, prior to transfer. The data packet is required to be an exact multiple of the payload specified by TXMAXP.

For Isochronous/Interrupts endpoints operating in Hi-Speed mode, MULT may be either 2 or 3 and specifies the maximum number of such transactions that can take place in a single microframe.

bit 10-0 **RXMAXP<10:0>:** Maximum RX Payload Per Transaction Control bits

This field sets the maximum payload (in bytes) transmitted in a single transaction. The value is subject to the constraints placed by the USB Specification on packet sizes for Bulk, Interrupt and Isochronous transfers in Full-Speed and Hi-Speed operations.

RXMAXP must be set to an even number of bytes for proper interrupt generation in DMA Mode 1.

TABLE 12-13: PERIPHERAL PIN SELECT INPUT REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1488	U5RXR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U5RXR<3:0>				0000
148C	U5CTSR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U5CTSR<3:0>				0000
1490	U6RXR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U6RXR<3:0>				0000
1494	U6CTSR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U6CTSR<3:0>				0000
149C	SDI1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI1R<3:0>				0000
14A0	SS1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS1R<3:0>				0000
14A8	SDI2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI2R<3:0>				0000
14AC	SS2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS2R<3:0>				0000
14B4	SDI3R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI3R<3:0>				0000
14B8	SS3R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS3R<3:0>				0000
14C0	SDI4R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI4R<3:0>				0000
14C4	SS4R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS4R<3:0>				0000
14CC	SDI5R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI5R<3:0>				0000
14D0	SS5R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS5R<3:0>				0000
14D8	SDI6R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI6R<3:0>				0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 12-13: PERIPHERAL PIN SELECT INPUT REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
14DC	SS6R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS6R<3:0>				0000
14E0	C1RXR(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	C1RXR<3:0>				0000
14E4	C2RXR(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	C2RXR<3:0>				0000
14E8	REFCLKI1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	REFCLKI1R<3:0>				0000
14F0	REFCLKI3R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	REFCLKI3R<3:0>				0000
14F4	REFCLKI4R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	REFCLKI4R<3:0>				0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

16.0 OUTPUT COMPARE

Note: This data sheet summarizes the features of the PIC32MZ Graphics (DA) Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 16. "Output Compare"** (DS60001111), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

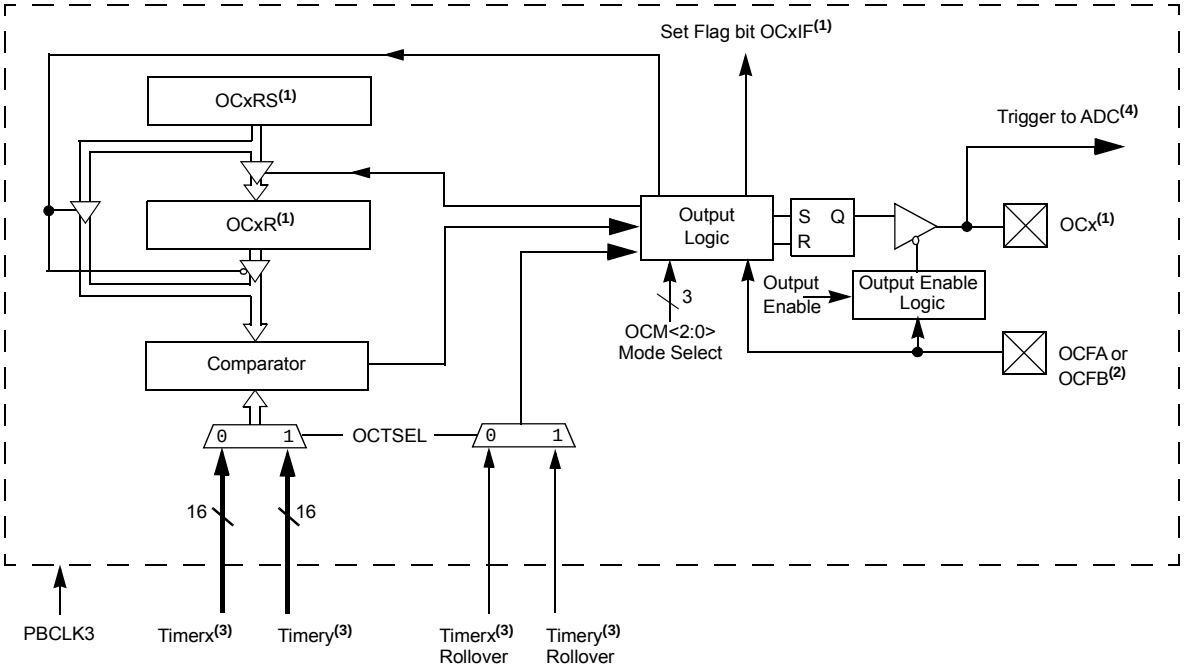
The Output Compare module is used to generate a single pulse or a train of pulses in response to selected time base events.

For all modes of operation, the Output Compare module compares the values stored in the OCxR and/or the OCxRS registers to the value in the selected timer. When a match occurs, the Output Compare module generates an event based on the selected mode of operation.

The following are some of the key features of the Output Compare module:

- Multiple Output Compare modules in a device
- Programmable interrupt generation on compare event
- Single and Dual Compare modes
- Single and continuous output pulse generation
- Pulse-Width Modulation (PWM) mode
- Hardware-based PWM Fault detection and automatic output disable
- Programmable selection of 16-bit or 32-bit time bases
- Can operate from either of two available 16-bit time bases or a single 32-bit time base
- ADC event trigger

FIGURE 16-1: OUTPUT COMPARE MODULE BLOCK DIAGRAM



Note 1: Where 'x' is shown, reference is made to the registers associated with the respective output compare channels, 1 through 9.

2: The OCFA pin controls the OC1, OC3, and OC7-OC9 channels. The OCFB pin controls the OC4-OC6 channels.

3: Refer to Table 16-1 for Timerx and Timery selections.

4: The ADC event trigger is only available on OC1,OC3, and OC 5.

32.1 Comparator Control Registers

TABLE 32-1: COMPARATOR REGISTER MAP

Virtual Address (BF84_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
C000	CM1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>		00C3
C010	CM2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>		00C3
C060	CMSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	C2OUT	C1OUT	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

NOTES:

REGISTER 38-6: DDRMEMCFG0: DDR MEMORY CONFIGURATION REGISTER 0

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	APCHRGEN	—	CLHADDR<4:0>				
23:16	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	CSADDR<4:0>				
15:8	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	BNKADDR<4:0>				
7:0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	RWADDR<4:0>				

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **Unimplemented:** Read as '0'

bit 30 **APCHRGEN:** Automatic Precharge Enable bit

When set, this bit issues an auto-precharge command to close the bank at the end of every user command. If the command accesses more than one bank before completing, all banks accessed are auto-precharged.

1 = Issue an auto-precharged command

0 = Do not issue an auto-precharged command

bit 29 **Unimplemented:** Read as '0'

bit 28-24 **CLHADDR<4:0>:** Column Address Shift bits

These bits specify how many bits the controller address must be right-shifted to put the high part of the column address to the immediate left of the low part of the column address. Used in conjunction with CLADDRHMSK (DDRMEMCFG2<26:0>) and CLADDRLMASK (DDRMEMCFG3<26:0>).

bit 23-21 **Unimplemented:** Read as '0'

bit 20-16 **CSADDR<4:0>:** Chip Select Shift bits

These bits specify which bits of user address space are used to derive the Chip Select address for the DDR memory. Used in conjunction with CSADDRMASK (DDRMEMCFG4<10:8>).

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **BNKADDR<4:0>:** Bank Address Select Shift bits

These bits specify which bits of user address space are used to derive the bank address for the DDR memory. Used in conjunction with BNKADDRMASK (DDRMEMCFG4<2:0>).

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **RWADDR<4:0>:** Row Address Select Shift bits

These bits specify which bits of user address space are used to derive the row address for the DDR memory. Used in conjunction with RWADDRMSK (DDRMEMCFG1<12:0>).

NOTES:

44.1 DC Characteristics

TABLE 44-1: OPERATING MIPS VS. VOLTAGE

Characteristic	V_{DDIO} Range (in Volts) (Note 1)	V_{DDCORE} Range (in Volts) (Note 1)	Temp. Range (in °C)	Max. Frequency	Comments
				PIC32MZ DA Devices	
DC5	2.2V-3.6V	1.7V-1.9V	-40°C to +85°C	200 MHz	—

Note 1: Overall functional device operation below operating voltages guaranteed (but not characterized) until Reset is issued. All device Analog modules, when enabled, will function, but with degraded performance below operating voltages. Refer to Table 44-5 for Reset values.

TABLE 44-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typ.	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	T_J	-40	—	+125	°C
Operating Ambient Temperature Range	T_A	-40	—	+85	°C
Power Dissipation: Internal Chip Power Dissipation: $P_{INT} = V_{DDIO} \times (I_{DD} - S\ I_{OH})$ I/O Pin Power Dissipation: $P_{I/O} = S\ (\{V_{DDIO} - V_{OH}\} \times I_{OH}) + S\ (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 44-3: THERMAL PACKAGING CHARACTERISTICS

Characteristics	Symbol	Typ.	Max.	Unit	Notes
Package Thermal Resistance, 169-pin LFBGA (11x11x1.4 mm)	θ_{JA}	25	—	°C/W	**1**
Package Thermal Resistance, 169-pin LFBGA (11x11x1.56 mm)	θ_{JA}	24	—	°C/W	**1,2**
Package Thermal Resistance, 176-pin LQFP (20x20x1.45 mm)	θ_{JA}	17	—	°C/W	**1**
Package Thermal Resistance, 176-pin LQFP (20x20x1.45 mm)	θ_{JA}	19	—	°C/W	**1,2**
Package Thermal Resistance, 288-pin LFBGA (15x15x1.4 mm)	θ_{JA}	22	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-$_{JA}$ (θ_{JA}) numbers are achieved by package simulations.

2: Devices with internal DDR2 SDRAM.

FIGURE 44-5: EXTERNAL RESET TIMING CHARACTERISTICS

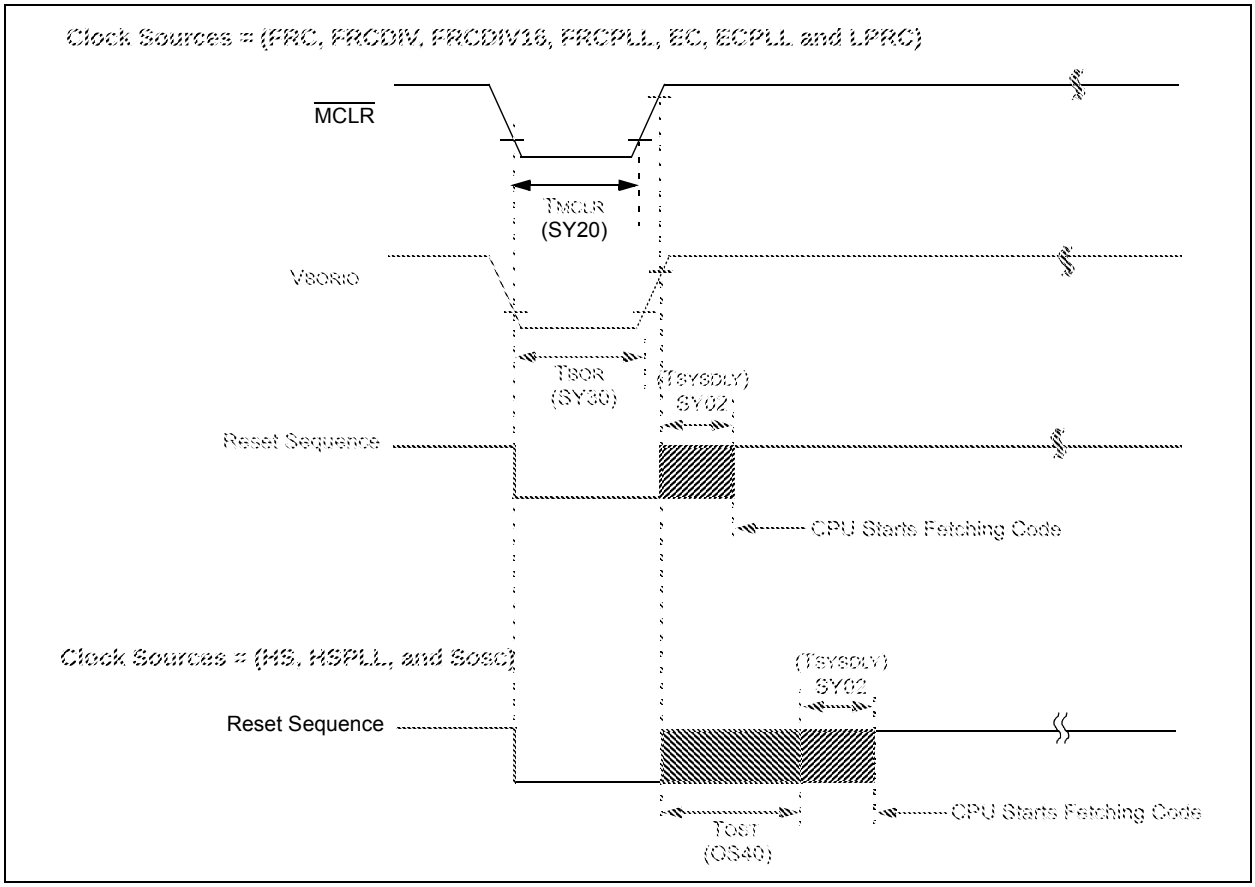


TABLE 44-31: RESETS TIMING

AC CHARACTERISTICS			Standard Operating Conditions: V_{DDIO} = 2.2V to 3.6V, V_{DDCORE} = 1.7V to 1.9V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SY00	TPU	Power-up Period Internal Voltage Regulator Enabled	—	400	600	µs	—
SY02	TSYSDLY	System Delay Period: Time Required to Reload Device Configuration Fuses plus SYSCLK Delay before First instruction is Fetched.	—	1 µs + 8 SYSCLK cycles	—	—	—
SY20	TMCLR	$\overline{MCLR}$ Pulse Width (low)	2	—	—	µs	—
SY30	TBOR	BOR Pulse Width (low)	—	1	—	µs	—

Note 1: These parameters are characterized, but not tested in manufacturing.
2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated. Characterized by design but not tested.

TABLE 44-48: TEMPERATURE SENSOR SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: V_{DDIO} = 2.2V to 3.6V, V_{DDCORE} = 1.7V to 1.9V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TS10	VTS	Rate of Change	—	5	—	mV/ºC	—
TS11	TR	Resolution	-2	—	+2	ºC	—
TS12	IVTEMP	Voltage Range	0.5	—	1.5	V	—
TS13	TMIN	Minimum Temperature	—	-40	—	ºC	IVTEMP = 0.5V
TS14	TMAX	Maximum Temperature	—	160	—	ºC	IVTEMP = 1.5V

Note 1: The temperature sensor is functional at VBORIOMIN < VDDIO < VDDIOMIN, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

45.0 AC AND DC CHARACTERISTICS GRAPHS

Note: The graphs provided are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 45-1: VOH – 4x DRIVER PINS

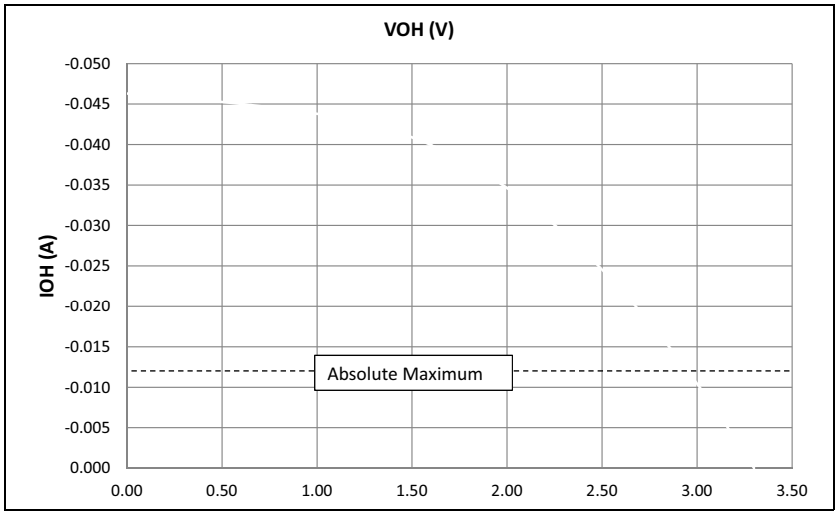


FIGURE 45-2: VOL – 4x DRIVER PINS

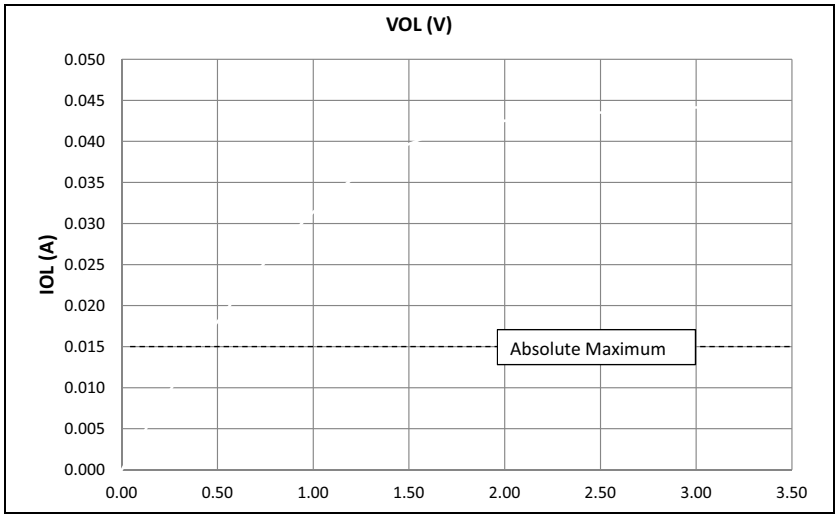


FIGURE 45-3: VOH – 8x DRIVER PINS

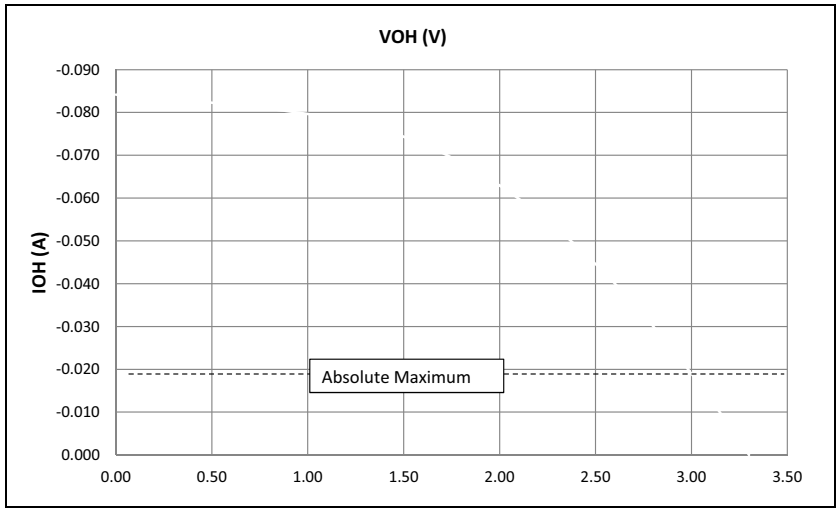


FIGURE 45-4: VOL – 8x DRIVER PINS